

SHINDENGEN

General Purpose Rectifiers

SMT Bridges

S1ZB60

600V 0.8A

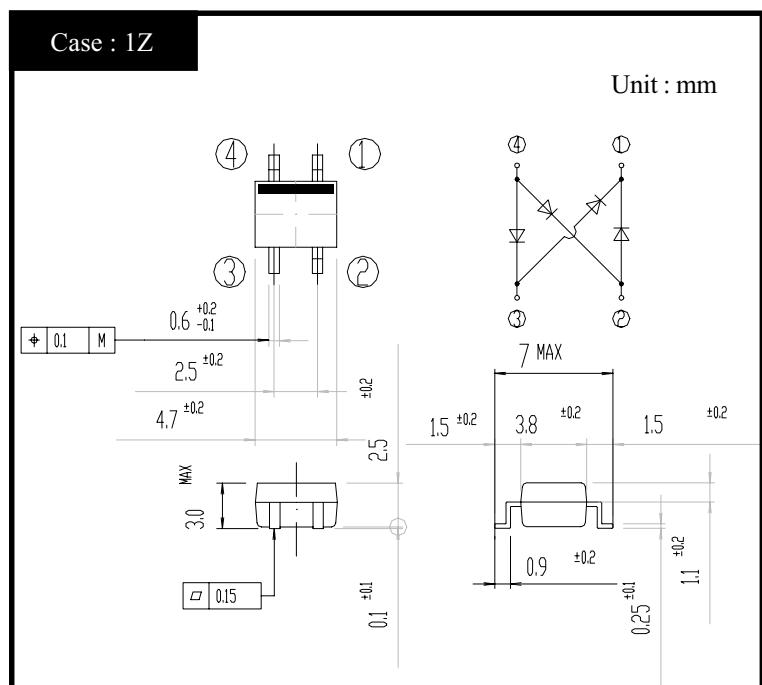
FEATURES

- Small SMT package
- High reliability with superior moisture resistance
- Applicable to Automatic Insertion

APPLICATION

- Switching power supply
- Home Appliances, Office Equipment
- Telecommunication, Factory Automation

OUTLINE DIMENSIONS



RATINGS

● Absolute Maximum Ratings (If not specified $T_J=25^\circ\text{C}$)

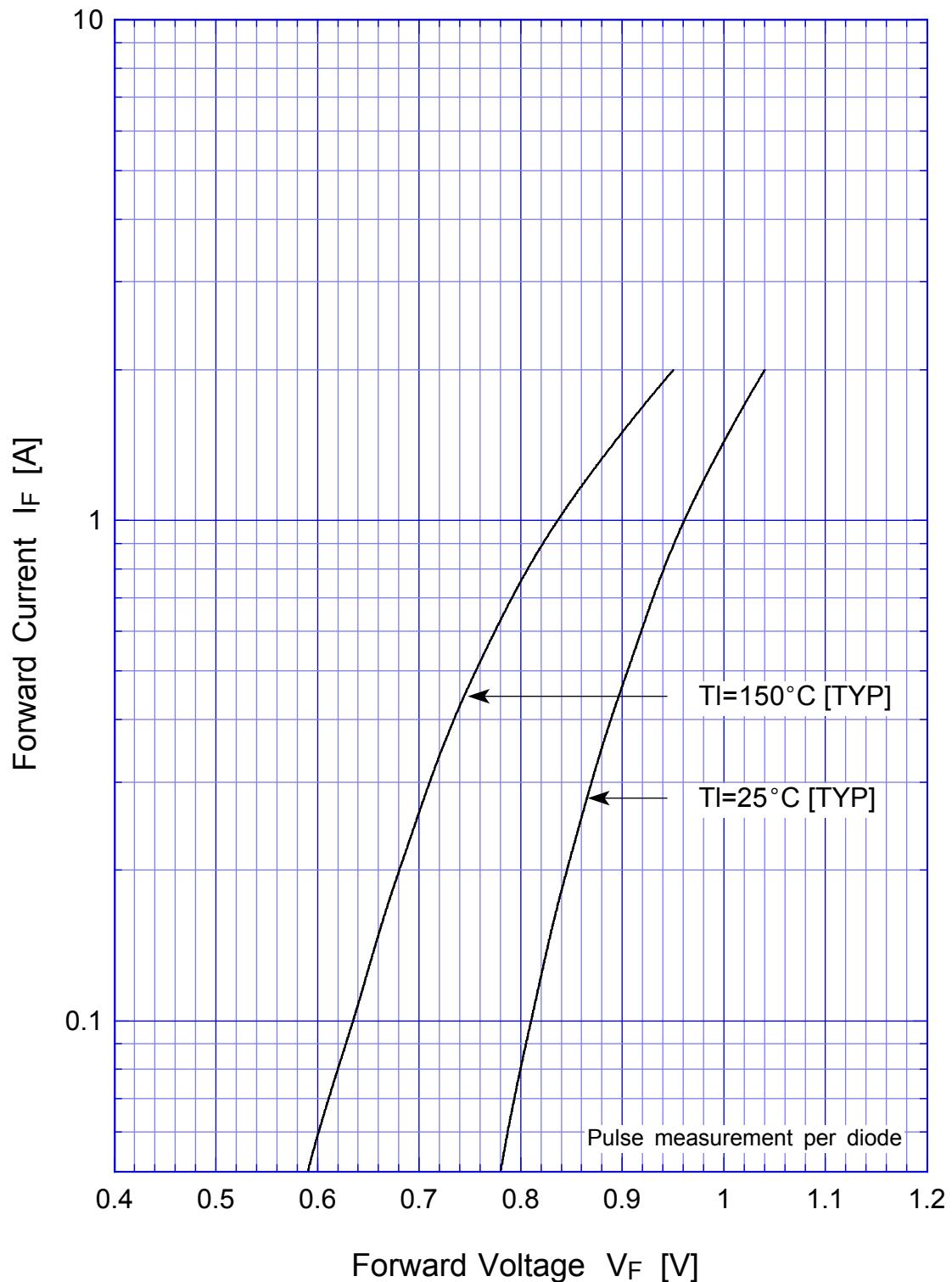
Item	Symbol	Conditions	Ratings	Unit
Storage Temperature	T_{stg}		-40~150	$^\circ\text{C}$
Operating Junction Temperature	T_J		150	$^\circ\text{C}$
Maximum Reverse Voltage	V_{RM}		600	V
Average Rectified Forward Current	I_O	50Hz sine wave, R-load On alumina substrate $T_a=25^\circ\text{C}$	0.8	A
		50Hz sine wave, R-load On glass-epoxy substrate $T_a=25^\circ\text{C}$	0.5	
Peak Surge Forward Current	I_{FSM}	50Hz sine wave, Non-repetitive 1 cycle peak value, $T_J=25^\circ\text{C}$	30	A
Current Squared Time	I^2t	$1\text{ms} \leq t < 10\text{ms}$ $T_J=25^\circ\text{C}$	4.5	A^2s

● Electrical Characteristics (If not specified $T_J=25^\circ\text{C}$)

Item	Symbol	Conditions	Ratings	Unit
Forward Voltage	V_F	$I_F=0.4\text{A}$, Pulse measurement, Rating of per diode	Max.1.05	V
Reverse Current	I_R	$V_R=V_{\text{RM}}$, Pulse measurement, Rating of per diode	Max.10	μA
Thermal Resistance	θ_{JL}	junction to lead	Max.20	
	θ_{JA}	junction to ambient On alumina substrate	Max.76	$^\circ\text{C}/\text{W}$
		junction to ambient On glass-epoxy substrate	Max.134	

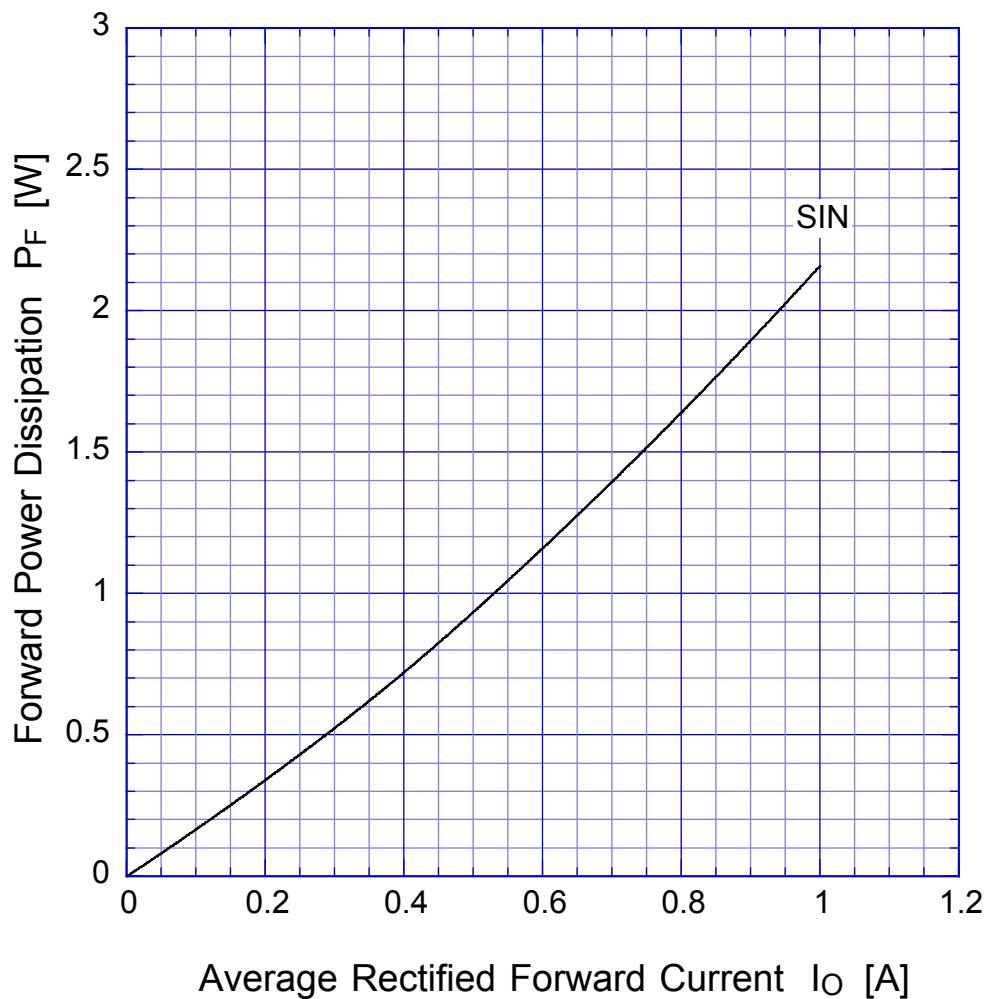
S1ZBx

Forward Voltage

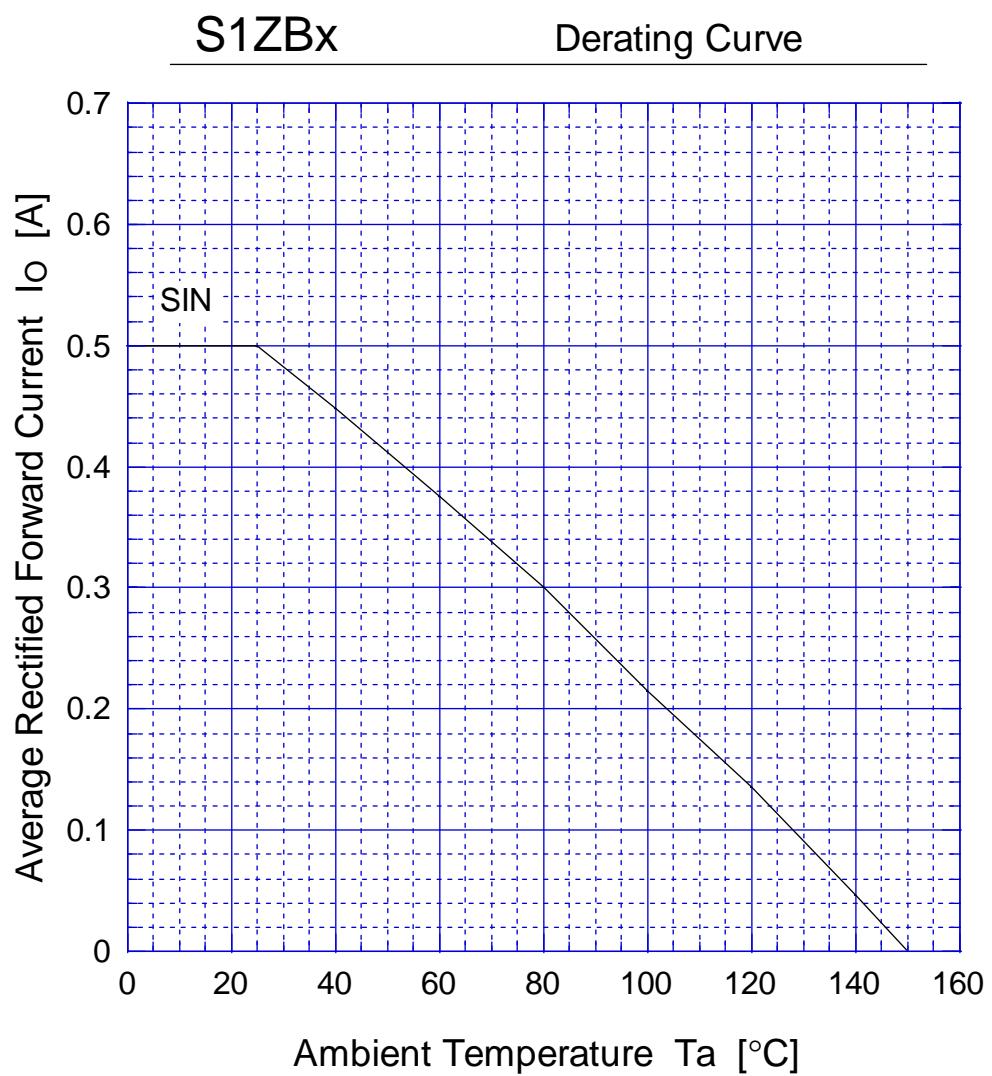


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Forward Power Dissipation



$T_j = 150^\circ\text{C}$
Sine wave



Sine wave
 R-load
 Free in air

	Glass-epoxy	Alumina
Soldering land	1mm×1mm	1mm×1mm
Conductor layer	35µm	20µm
Substrate thickness		0.64mm

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Peak Surge Forward Capability

